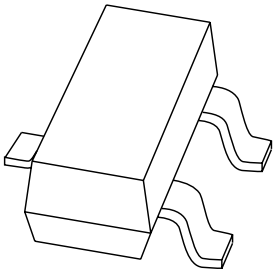
DATA SHEET



BCW31; BCW32; BCW33
NPN general purpose transistors

Product data sheet
Supersedes data of 2000 Jul 04

2004 Feb 06

NPN general purpose transistors

BCW31; BCW32; BCW33

FEATURES

- Low current (100 mA)
- Low voltage (32 V).

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

NPN transistors in a plastic SOT23 package.
PNP complements: BCW29 and BCW30.

MARKING

TYPE NUMBER	MARKING CODE(1)
BCW31	D1*
BCW32	D2*
BCW33	D3*

Note

1. * = p : Made in Hong Kong.
   * = t : Made in Malaysia.
   * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

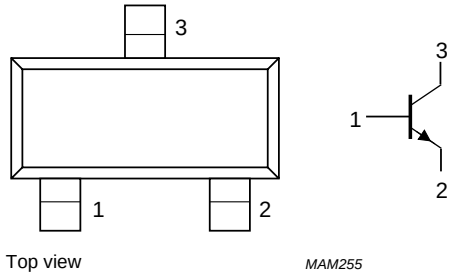


Fig.1 Simplified outline (SOT23) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCW31	–	plastic surface mounted package; 3 leads	SOT23
BCW32			
BCW33			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	32	V
V_{CEO}	collector-emitter voltage	open base; I_C = 2 mA	–	32	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	100	mA
I_{CM}	peak collector current		–	200	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	–	250	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		−65	+150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

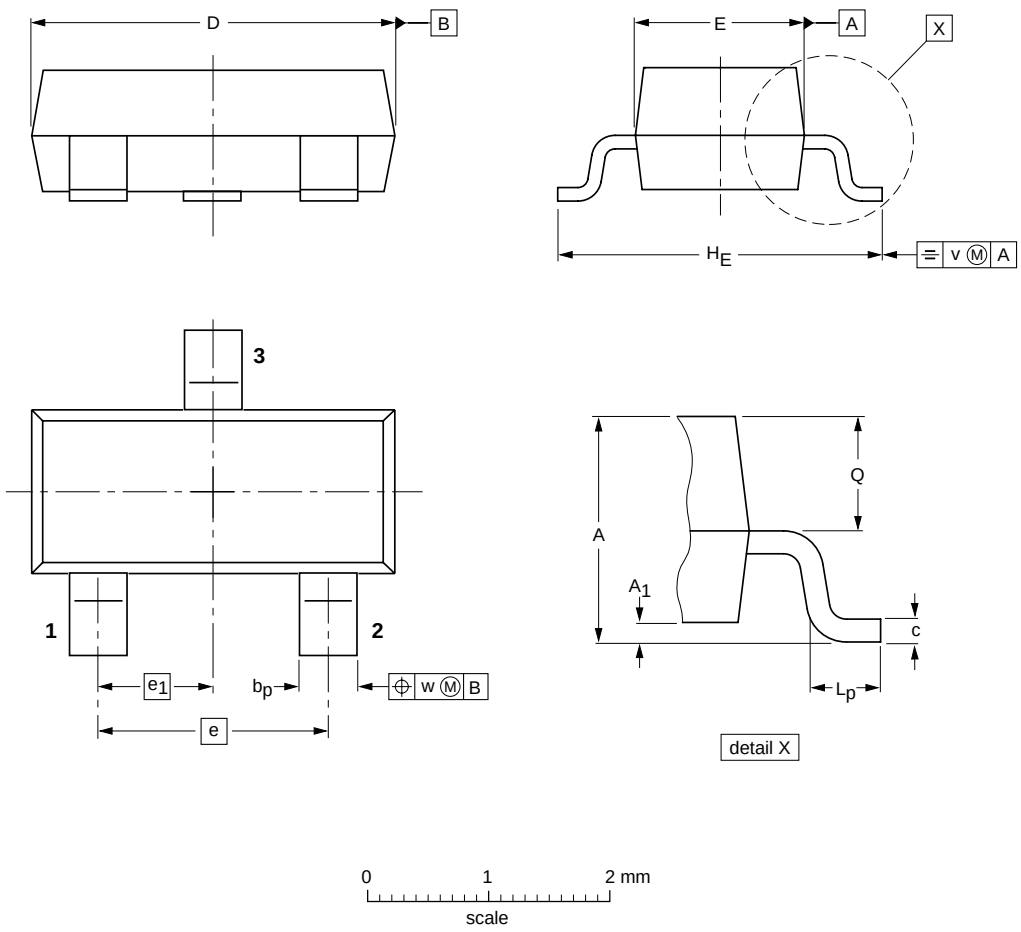
CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = 32 V	–	–	100	nA
		I_E = 0; V_{CB} = 32 V; T_j = 100 °C	–	–	10	μA
I_{EBO}	emitter cut-off current	I_C = 0; V_{EB} = 5 V	–	–	100	nA
h_{FE}	DC current gain	I_C = 10 μA; V_{CE} = 5 V				
	BCW31		–	190	–	
	BCW32		–	330	–	
	BCW33		–	600	–	
	DC current gain	I_C = 2 mA; V_{CE} = 5 V				
	BCW31		110	–	220	
	BCW32		200	–	450	
	BCW33		420	–	800	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA	–	120	250	mV
		I_C = 50 mA; I_B = 2.5 mA	–	210	–	mV
V_{BEsat}	base-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA	–	750	–	mV
		I_C = 50 mA; I_B = 2.5 mA	–	850	–	mV
V_{BE}	base-emitter voltage	I_C = 2 mA; V_{CE} = 5 V	550	–	700	mV
C_c	collector capacitance	$I_E = I_e$ = 0; V_{CB} = 10 V; f = 1 MHz	–	2.5	–	pF
f_T	transition frequency	I_C = 10 mA; V_{CE} = 5 V; f = 100 MHz	100	–	–	MHz
F	noise figure	I_C = 200 μA; V_{CE} = 5 V; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz	–	–	10	dB

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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Printed in The Netherlands R75/05/pp6 Date of release: 2004 Feb 06 Document order number: 9397 750 12404

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